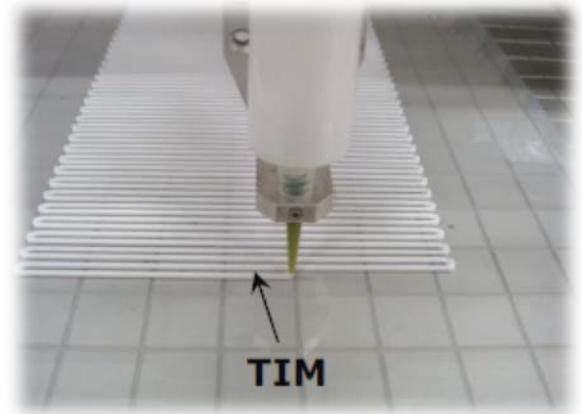


FOR IMMEDIATE RELEASE:

PRE-CURED, SINGLE-COMPONENT SILICONE SOLUTION MINIMIZES THE MIX: SHIN-ETSU SILICONES LAUNCHES CLG SERIES GAP FILLERS WITH IMPROVED RESISTANCE AGAINST PUMP-OUT FOR ADVANCED THERMAL MANAGEMENT ELECTRONICS APPLICATIONS.

Akron, OH—February 2018

In an effort to provide progressive options to thermal engineers in the growing electronics cooling market sector for silicone TIM (Thermal Interface Materials), Shin-Etsu Silicones of America, Inc. (SESA: A U.S. subsidiary of Shin-Etsu Chemical Co. Ltd., Japan) recently premiered its CLG Series single-component, pre-cured Gap Filler product line. SESA’s CLG Series materials are ideal for a broad base of general electronics cooling applications—offering a wide range of thermal conductivity.



CLG SERIES PROFILE: (CLG-1500, CLG-2500, CLG-3500, CLG-4500)

The one-component CLG Gap Filler greases are simpler to use, requiring no mixing or use of a two-part meter-mix equipment system. Notably, the material does not need to cure after it is dispensed so there is no time-consuming waiting or heating involved to cure after dispensing—and no resulting curing process by-products. The materials offer a low volatile content with excellent resistance to pump-out and creeping.

Featuring a gel-like consistency, the material is applicable on a myriad of surface shapes—easily filling voids between heat sources and heat sinks. By displacing the air from these nooks-and-crannies, a lower thermal resistance is achieved. Notably, the CLG Gap Filler material can be applied only where you need it, thereby minimizing waste. The materials can also be reworked because they do not adhere to substrates. The soft material’s low hardness minimizes stress on delicate electronic components. Additionally, the viscosity allows for ease of dispensing, reduced process times, and there are no unique storage requirements.

SESA / CLG SERIES TYPICAL PROPERTIES		CLG-1500	CLG-2500	CLG-3500	CLG-4500
Appearance		White	White	White	White
Specific Gravity at 25°C		2.6	2.9	3.1	3.2
Viscosity @ 25°C	Pa-s	500	500	250	550
Thermal Conductivity	W/m-K	1.5	2.9	3.5	4.8
Dielectric breakdown strength	kV/mm	9.6	6.2	8.9	4.7
Operation temperature range	°C	-40 to +180	-40 to +180	-40 to +180	-40 to +180
LMW siloxane content	ΣD_3-D_{10} ppm	≤300	≤300	≤300	≤300



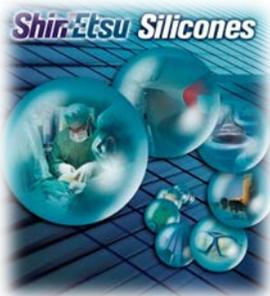
According to SESA's Thermal Interface Materials Business Development Manager, Geoff Thyrum, "As electronic devices shrink in size and expand in functionality, the requirements for thermal solutions are ever-increasing. The CLG Series' economical pre-cured and performance advantages will allow us to optimize new and existing client applications in the growing electronics cooling market segments."



Ultimately, the CLG Series represents a great addition to SESA's broad silicone TIM product line in North America, which includes products such as adhesives, soft pads, thermal greases, etc.

For more detailed information, visit the Shin-Etsu Silicones web site at:

http://www.shinetsusilicones.com/liquid_filler.html



CORPORATE PROFILE:

A U.S. subsidiary of Shin-Etsu Chemical Co. Ltd., Japan, Shin-Etsu Silicones of America Inc. offers vast technical and capital resources to formulate solutions as a major supplier of silicone materials to North America's medical, automotive, electronics, aerospace, cosmetics, and manufacturing industries. Shin-Etsu's premium silicone compounds incorporate leading-edge technology, staff expertise, and value-added service; offering customers the highest levels of quality and consistency in specialty silicone materials.

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